



FY2011Outlook

June8,2011

@Hitachi High-Technologies Corporation

President, Chief Executive Officer Masao Hisada

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Contents



FY2011Outlook

I FY11ManagementPolicy

I FY11Outlook

I FY11ManagementPolicy

(Note)YY/Mdenotestheyearandmonthoftheaccounti

ngperiod-end.

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FY11ManagementPolicies



Achieveourcorporatevision ToconsistentlyaimtobeGlobalTopinhigh-techs olutions

- 1.Shiftourresourcestogrowingmarketanddevelopnew businessmodels
- 2.Transformtohigh-profitablestructuresbybuilding upourglobalbusinesses
- 3.Createstrongermanagementfoundationforthenex tgrowth
- 4. Strengthenour consolidated management and cashflow management
- 5.PromoteCSR-consciousmanagementandfosterouremplo yees

Ourrestorationstatus aftertheGreatEastJapanEa

rthquake



RestorationstatusofHitachiHigh-TechNakaDivisionand HitachiHigh-TechManufacturing&ServiceCorporation

- 1.Restorationstatusofbuildings
- Completedrelocationandstartedupallworkplacesfrom May6th.
- Changedareconstructionplanforearthquake-resistantbu ildingsand improvingmanufacturingsitesstartedsinceFY08.HitachiH igh-Tech willmakeadditionalinvestment(approximately5billi onyenintotal)and buildnewbuildingstopromotehighermanufacturinge fficiencyandabilities.
- 2. Manufacturing status

ByJune, build up more manufacturing a bilities as well and start production increases from July.

aslogisticsabilities



StatusofSupplyChain

SupplyChainhasbeenimprovedrapidlyinJapan.Hitach willcontinuetosourcepartsfromothersuppliersaswell tominimizerisks.

iHigh-Technologies asconsideralternatives

PowerConservationMeasures

■ HitachiHigh-TechwilljoinHitachiGroup'sco-strategies andsummerholidaydistribution.Moreover,HitachiHigh strategiesandachieve15% (see ref1) powersavingintotal.

mlastyearneedtobecutinTokyoElectricPower

Company and Tohoku Electric Power

ofholidayshiftrotations

-Techwillcarryoutown

Ref1:Morethan15%ofmaximumelectricusagefro Corporationareas. (TokyoElectricPowerCompanyarea:fromJul1st

to Sep 22nd, 2011, Tohoku Electric Power Corporat

ionarea:fromJul1sttoSep9th,2011)

■ Considerationofindependentelectronicpowerequipmen becontinuedbycheckingrelatedlegalissuesforBCP'spoi

tinstallationwill ntofview.

II FY11Outlook

(Note) YY/M denotes the year and month of the accounting the property of the

ngperiod-end.

FY11Outlook(Highlights)



(100millionyen)

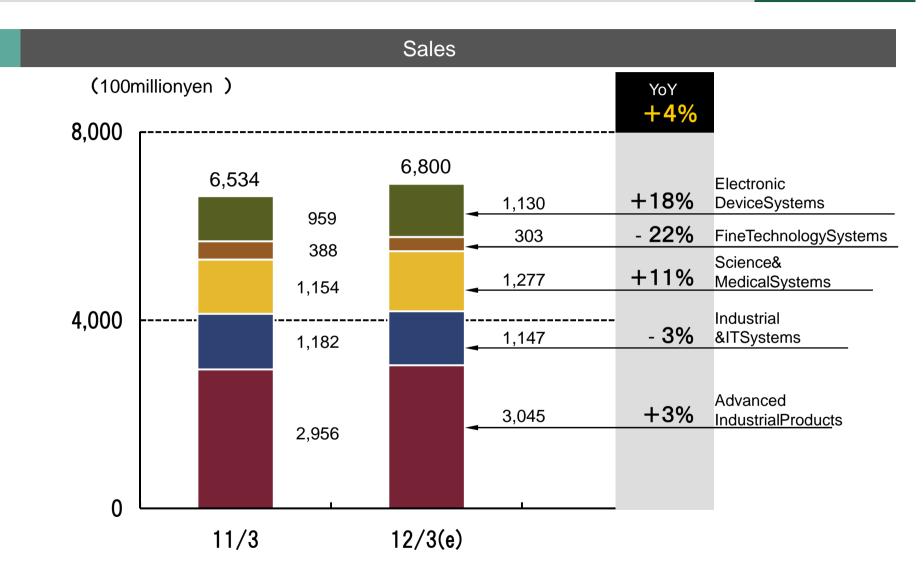
	FY10Outlook	FY10Results	YoY	
	1 1 100 011001	1 1 TORCOURS	Increase/Decrease	Ratio
Sales	6,800	6,534	+266	+4%
OperatingIncome	280	279	+1	+0%
OrdinaryIncome	280	295	-15	-5%
NetIncome	180	178	+2	+1%
NetIncome perShare	130.87 yen	129.07 yen	+1.80ye	
CashDividend perShare	20 . 00 yen	20 . 00 yen	±0.00 yen	
ROE	7.2%	7.5%	-0.3%	
FIV	+44	+59	-15	
FCF	+150	+221	-7	

FXRateEstimate: 1USD=80 yen

1EUR=115 yen

FY11Outlook(SalesbySegment)

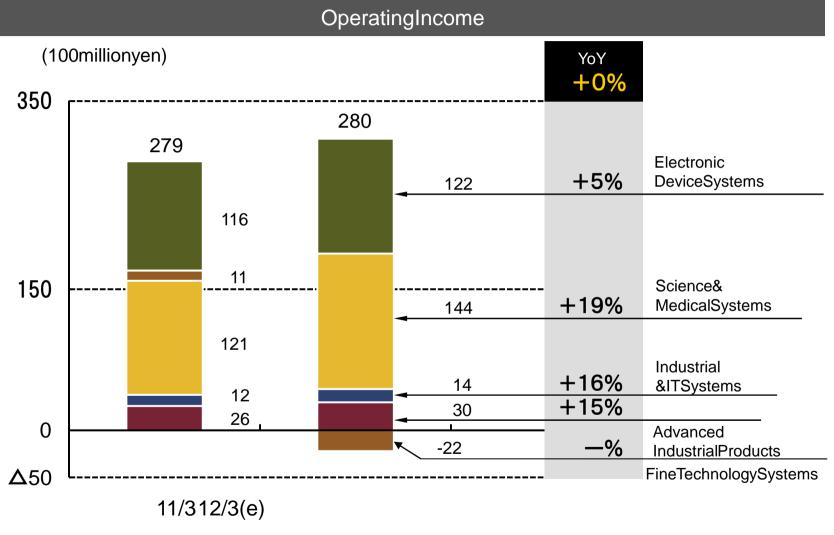




Note: Elimination such as intersegment transaction setc. ar eincluded in the totals.

FY11Outlook(OperatingIncomebySegment)





Note: Elimination such as intersegment transaction setc. ar eincluded in the totals.

FY11Outlook(ElectronicDeviceSystems)





SemiconductorrelatedmarketstatusinFY11

SemiconductorDevicesMarket

- Approximately6%marketgrowthcanbeexpecteddue mobilerelatedproductsincludingsmartphones,tabl
- MarketsforNAND,MPUandASSPwillcontinuetogro wasbetween-10%to-15%asdemandforPChasbeen However,demandformobileDRAMwillincrease.
- EffectoftheGreatEastJapanEarthquaketoglobal

toincreasingshipmentsof etsandsooninFY11.

winFY11.GrowthforDRAM declinedsinceFY10/2H.

marketwillbelimited.

SemiconductorManufacturingEquipmentMarket

- Themarketkeptgrowingin4QofFY10,whichwasth
- InFY11,approximately7%ofmarketgrowthcanbee beplanedinFY11/2Hduetotheeffectofpositive
- Investmentformassproductionoflogic,MPUandNA fab constructionofMPUandNANDmanufacturesandfo

e7thsuccessfulterm.

xpected.Capitalinvestmentwill

investmentinFY10/2H.

ND(2Xnm)willincrease.New undrieswillbeplaned.

AssemblyEquipmentMarket

Althoughthenumberofshipmentswillincreasepart marketsizeincashwillbeeguivalenttotheonei

icularlyinChinesemarketinFY11, nFY10duetodeflationofASP.

FY11Outlook(ElectronicDeviceSystems)





TrendofSemiconductorDeviceScaling

Expectationtosemiconductordevicesand processtechnologies

Mobilerelateddevicessuchassmartphones and tabletswilldrivesemiconductortechnologies.

- Miniaturizationandreductionoffootprintwillbe acceleratedduetoscaling.
- Reductionofpowerconsumptionrelatedtolower poweroperation.(Table1)

Trendofnextgenerationtransistortechnologies

- Trendwillmoveonfromthecurrentplanartypeto 3DFinFET (see Note) transistortoachievescalingandlow poweroperation.
- Doublepatterning(DP)isappliedforscaling.

Strategiestohandlefuturesemiconductor process

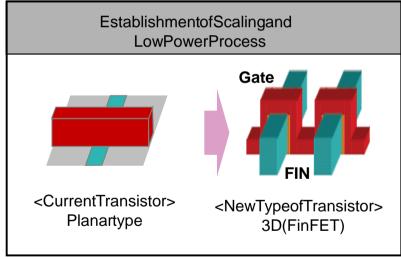
- Establishhighperformanceetchingtechnologiesfor
- Establishhighperformancemetrologytechnologiesf
- Co-developmentwithdevicemanufacturers.
- Establishdefectreviewtechnologiesforscaling.

Note: FinFET: Fin-type Field Effect Transistor

Table1.PowerConsumptionTrend (logic) comparisonwith2011

year	2011	2012	2013	2014	2015	2016
ITRS 2009 version	1	0.94	0.90	0.84	0.76	0.72
ITRS 2010version	1	0.94	0.68	0.56	0.54	0.46

ITRS: International Technology Roadmap for Semiconductors



FinFET. Lable2.

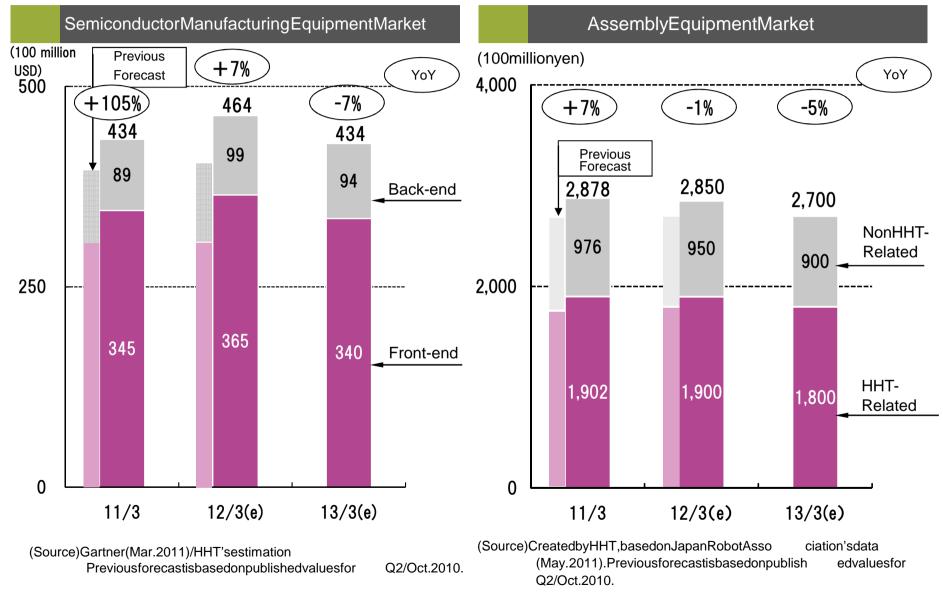
Table2.Comparisonofthenumberofgateprocess (estimatedbyHHT)

	Planartype (Current structure)	FINType (3D)	Targetmarketwillexpand forHitachiHigh-Technologies
Etching	8	10	duetointroductionof 3Dtransistor.
Metrology	14	16	SDITATISISIOT.

FY11Outlook(ElectricDeviceSystems)

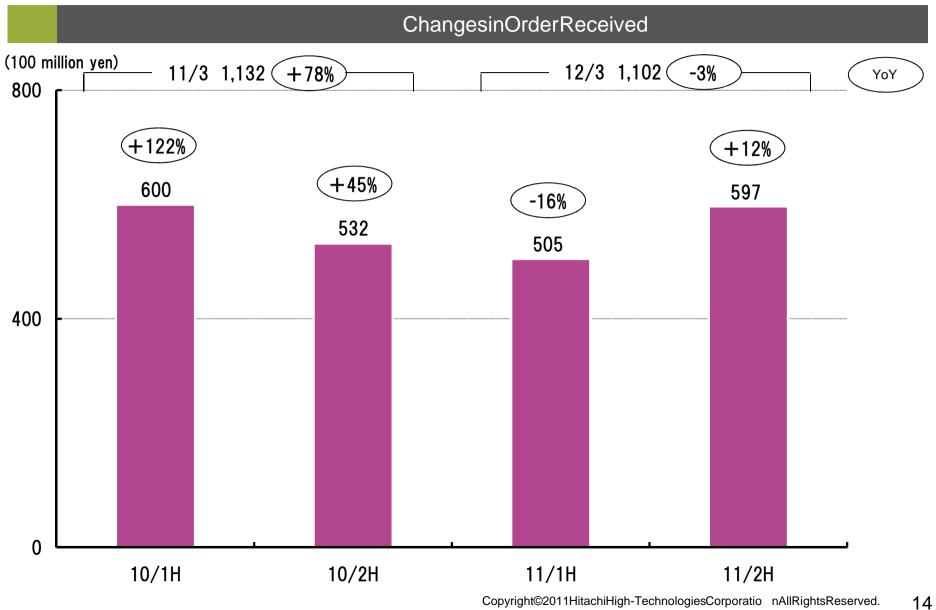






FY11Outlook(ElectricDeviceSystems)





4

FY11Outlook(ElectricDeviceSystems)





FY11Strategies

1. Expansionofsalesformainproductsandincreasi newproducts.

SalesChangeinMainBusinesses

2. Strengthenmarketing abilities and carryoutg

ngthenumberofcustomersbyreleasing

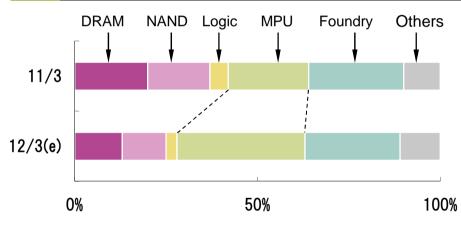
rowthstrategiesviaglobalmarketdevelopment.

(100millionyen) 1.200 1130 **Process** 959 +43% Equip. 372 261 Metrology& Inspection 600 +12% Equip. 477 427 Back-end& Assembly **+4%** Equip. 282 271 0

12/3(e)

11/3

SalesRatiobyFields(Front-endEquip.)



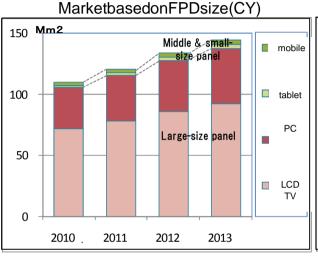
- FY10:Large-scaleinvestmentsrelatedto memorieswillbeexpectedin1H. Continuousinvestmentswillbeplaned infoundriesaswell.
- FY11:Ratiowillriseduetopositiveinvestments forMPU.Ratiorelatedtofoundrieswill alsogrow.

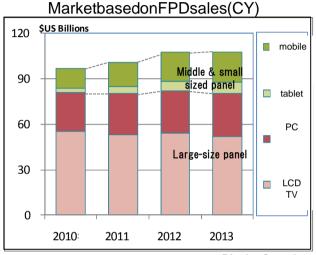


MarketStatusinFY11

TrendofFPDmarket

- Delayoftheexecution of investmentinChinadue toimpactofadownturnof large-sizepanelmarket.
- Continuous growth of marketrelatedtomiddle andsmall -sizepanelsfor mobileandtouchpanels





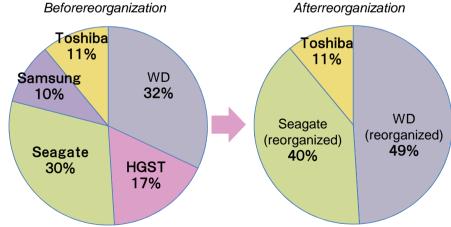
source: DisplaySearch

TrendofHDmarket

- Changesofbusinessenvironment duetoindustryreorganization
- AcquisitionofHGSTdonebyWD plannedin3QFY11
- AcquisitionofSamsung'sHDunit donebySeagaet plannedin Decemberin2011

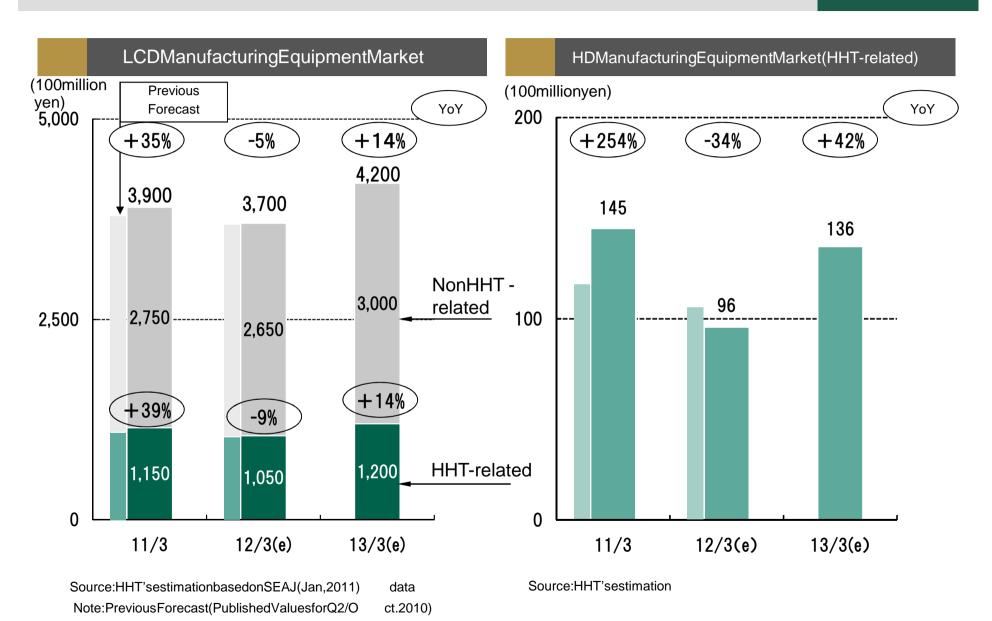
SharebasedonthenumberofshipmentofHDD

(1)



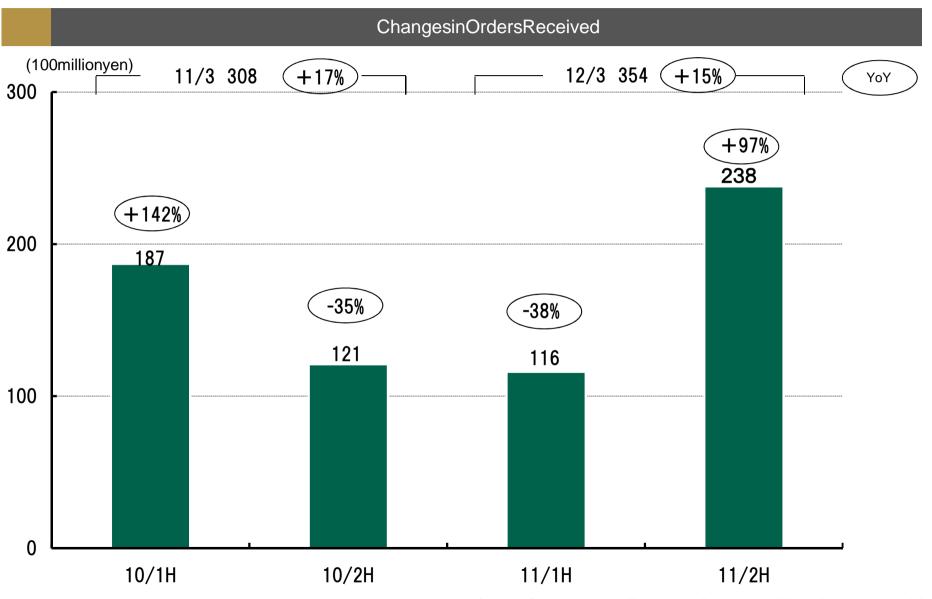
Source:InstituteofInformationTechnology,Ltd.1 1Q2(CY)Share Possibilitiesofmarketsharechanges





2



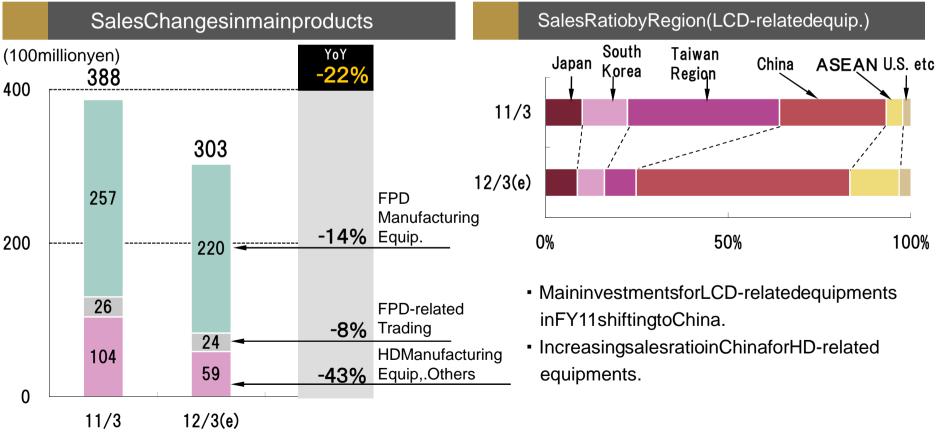






FY11Strategies

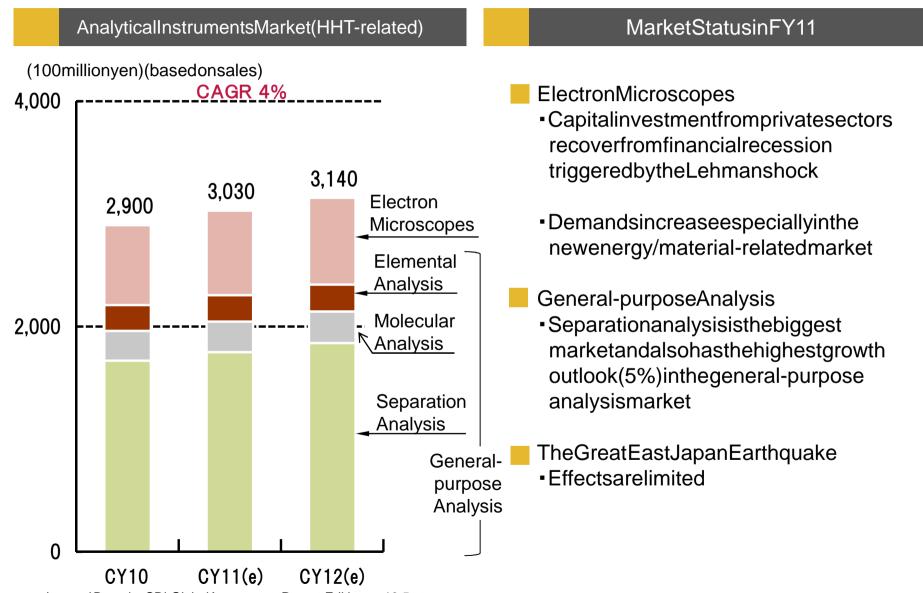
- 1.Expandbusinessesbyraisingcompetitivenessof existingproductsandintroducingnewproducts (new-typeLCDassemblysystems/HDinspectionequip ments)
- 2.Acceleratedevelopmentofnewbusinesses(OLEDm anufacturing/inspectionequipments)
- 3.Shiftabusinessstructurethatadaptstomarket changes (strengthenglobalsalespower/improvecost-compet itiveness)



FY11Outlook(Science&MedicalSystems) AnalyticalInstruments







FY11Outlook(Science&MedicalSystems) AnalyticalInstruments

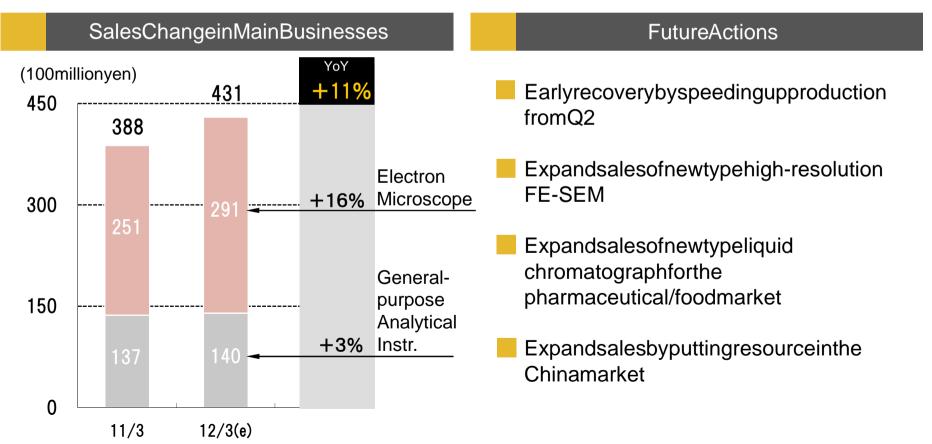




FY11Strategies

- 1.EarlyrecoveryfromtheGreatEastJapanEarthquake
- 2. Expands ales by introducing new products and putting

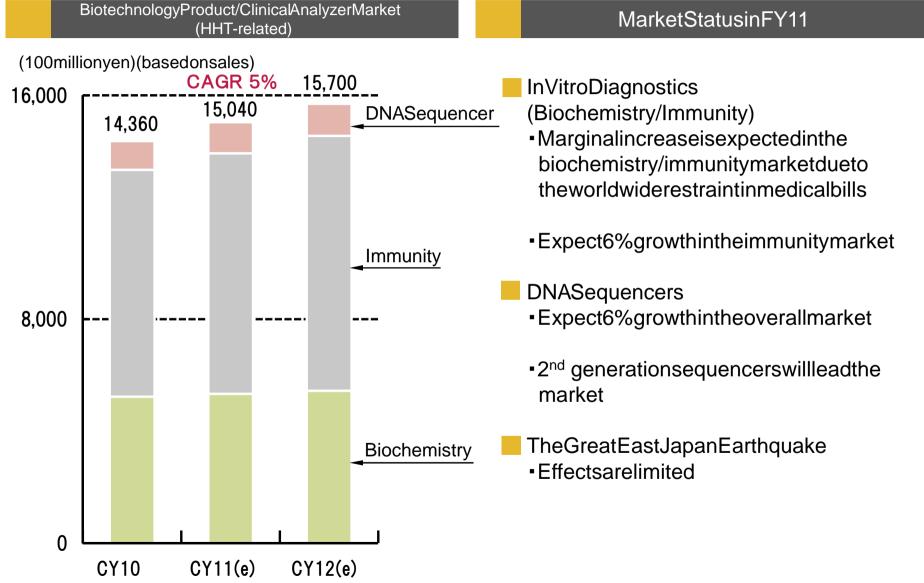
resourcein growingmarkets



FY11Outlook(Science&MedicalSystems) BiotechnologyProduct/ClinicalAnalyzer







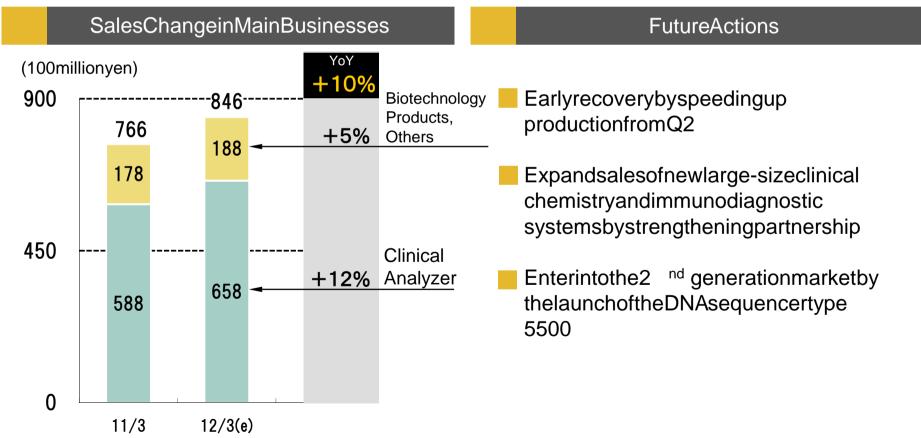
FY11Outlook(Science&MedicalSystems) BiotechnologyProduct/ClinicalAnalyzer





FY11Strategies

- 1.EarlyrecoveryfromtheGreatEastJapanEarthquake
- 2.ExpandsalesbypromotingSCBwithleadingcompanie s (SCB:SystemCollaborationBusiness)



FY11Outlook(Industrial&ITSystems) (AdvancedIndustrialProducts) 1



FY11Strategies

- 1. Shiftbusinessareastomarketswhere Hitachi Hi gh-Techisabletoa imglobaltop.
 - Createbusinesseswhichcanpromotecorecompetence
 - Shiftresourcestogrowingbusinessareasglobally
 - Promotebusinessdevelopmentwithlocalpartnersin targetareas.

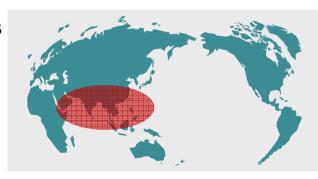
2. Stronglypromotebusinessestargeting Asianbelt areas.

note: Asiabeltareasinclude 24 countries/areasbe

tweenJapanandtheArabianPeninsulaasshownin

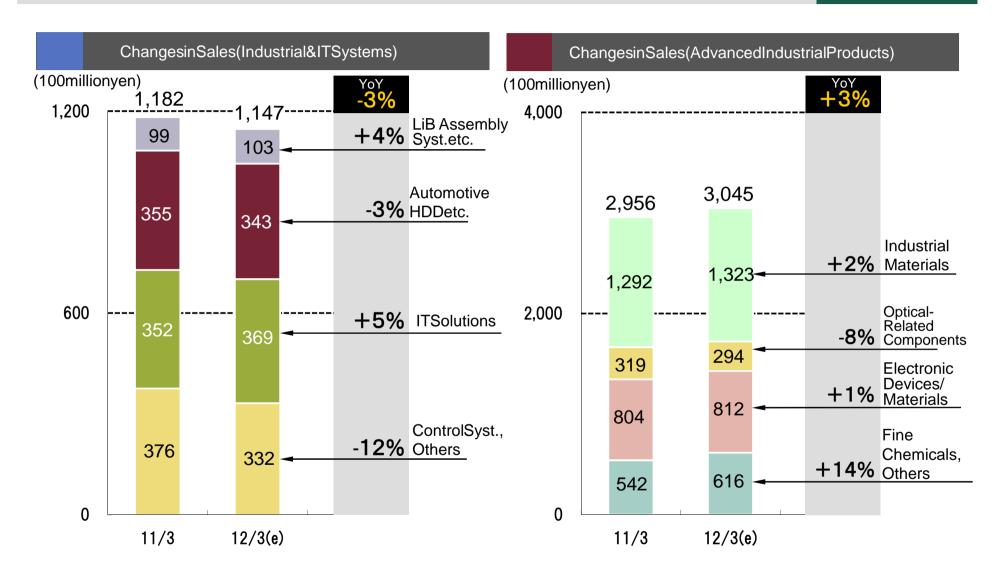
figurebelow.

- Expandalternativeenergyandwaterrelatedbusines ses inIndonesia.
- Promotebusinessdevelopmentrelatedtoautomotive aswellasalternativeenergyinIndia.



FY11Outlook(Industrial&ITSystems) (AdvancedIndustrialProducts) 2





CapitalExpenditure/DepreciationCosts/R&D



(100millionyen)

	10/3	11/3	YoY	12/3(e)	YoY
Capital Expenditure	94	90	-4%	184	+105%
Depreciation Costs	96	90	-7%	101	+12%
R&D	193	208	+8%	258	+24%

Note: Capital Expenditure is based on an acquisition ba

ses

Context(FY10)

CapitalExpenditure:9.4Ybnincrease

DesignBuildingconstructioninNakaDivision

R&D: 5.0Ybnincrease

Developmentofelementaltechnologiesinin-housem anufacturedequipments



Notesonthedata

ownjudgment.

- 1.Allfinancialstatementsummariesandresultspr Numericaldataisroundedofftothenearest100mi
- 2.Initsdisclosures, Hitachi High-Technologies ma respecttocertainfutureeventsandfinancialperf ofdisclosureandmaydifferfromactualresultsdu $items disclosed, the \hbox{\bar{C} ompany will disclose on a cas}$ exchangesonwhichtheCompanyislisted.

Theinformationincludedinthismaterialisforre

edictionsincludedinthispresentationareonaco llionyen. ymakestatementsthatconstituteforward-lookings ormanceatthetimeofdisclosure.Suchstatements

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tatementsthatreflectmanagement'sviewswith arebasedoninformationavailableatthetime rect.Intheeventofa majordiscrepancywiththe e-by-casebasisbasedonthelawand/orthetimely disclosurerulesandregulationsofthestock

nsolidatedbasisunless otherwisestated.

ferencewheninvesting, and not a can vas sto invest

. Brandselectionandthefinaldecisionisatyour



END

FY2011Outlook

Forfurtherinformation

HiroyukiKato

GeneralManager

CorporateCommunicationsDept.

CSRDiv.

TEL:03-3504-5138 FAX:03-3504-5943

E-mail:kato-hiroyuki@nst.hitachi-hitec.com

Hitachi High-Tech

Bringing the frontier to the forefront.